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(54) **METHOD FOR MANUFACTURING MULTILAYER
PRINTED WIRING BOARD**

minimum melting viscosity lies in the range of 200 Pa.s to 2,000 Pa.s.

(57) Abstract:

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PROBLEM TO BE SOLVED: To provide a method for manufacturing a multilayer printed wiring board, that can prevent scattering of adhesion force between a prepreg and an inner-layer copper foil and the decrease in the adhesion force, when producing the multilayer printed wiring board.

SOLUTION: In this method for manufacturing a multilayer printed wiring board, varnish containing a thermosetting resin constituent is impregnated into a glass cloth base before drying and cooling, a prepreg 1 where the thermosetting resin constituent has been semi-cured is created, and an inner-layer circuit- wiring board, having the prepreg and an inner-layer copper foil 6 subjected to roughing treatment by oxidation treatment is heated and pressurized for adhesion. In the method, when the temperature of the semi-cured thermosetting resin constituent of the prepreg to be used is increased at a temperature-increase rate of 3.0°C/minute, the

